

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC010N04LSC	**Issued**	02. June 2021
MA#	MA001709514		
Package	PG-TDSON-8-47	**Weight***	104.40 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.517	1.45	1.45	14533	14533
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		122	
	non noble metal	zinc	7440-66-6	0.051	0.05		487	
	non noble metal	iron	7439-89-6	1.016	0.97		9730	
	non noble metal	copper	7440-50-8	41.248	39.52	40.55	395096	405435
wire	noble metal	gold	7440-57-5	0.046	0.04	0.04	436	436
encapsulation	organic material	carbon black	1333-86-4	0.122	0.12		1170	
	plastics	epoxy resin	-	4.763	4.56		45627	
	inorganic material	silicondioxide	60676-86-0	35.827	34.32	39.00	343175	389972
leadfinish	non noble metal	tin	7440-31-5	1.084	1.04	1.04	10382	10382
plating	noble metal	silver	7440-22-4	0.197	0.19	0.19	1884	1884
solder	non noble metal	tin	7440-31-5	0.042	0.04		400	
	noble metal	silver	7440-22-4	0.052	0.05		501	
	non noble metal	lead	7439-92-1	1.996	1.91	2.00	19120	20021
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005			47	
	non noble metal	zinc	7440-66-6	0.020	0.02		189	
	non noble metal	iron	7439-89-6	0.394	0.38		3776	
	non noble metal	copper	7440-50-8	16.007	15.33	15.73	153325	157337
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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